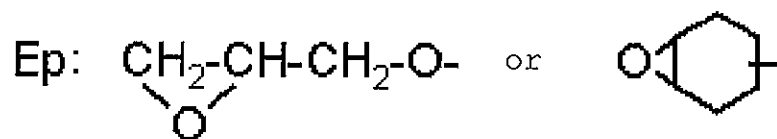


ABSTRACT

Disclosed is a semiconductor device configured by encapsulating a semiconductor element, partially or entirely covered with a polyimide, using an epoxy resin composition for encapsulating semiconductor device which contains an epoxy resin (A), a phenol resin (B), a curing accelerator (C), an inorganic filler (D), and a silane coupling agent (E) represented by the formula (1):



(in the formula (1), each of R^1 , R^2 and R^3 represents a C_{1-4} hydrocarbon group, all of them may be the same or different from each other, and n represents an integer from 0 to 2), and/or a hydrolytic condensate thereof.